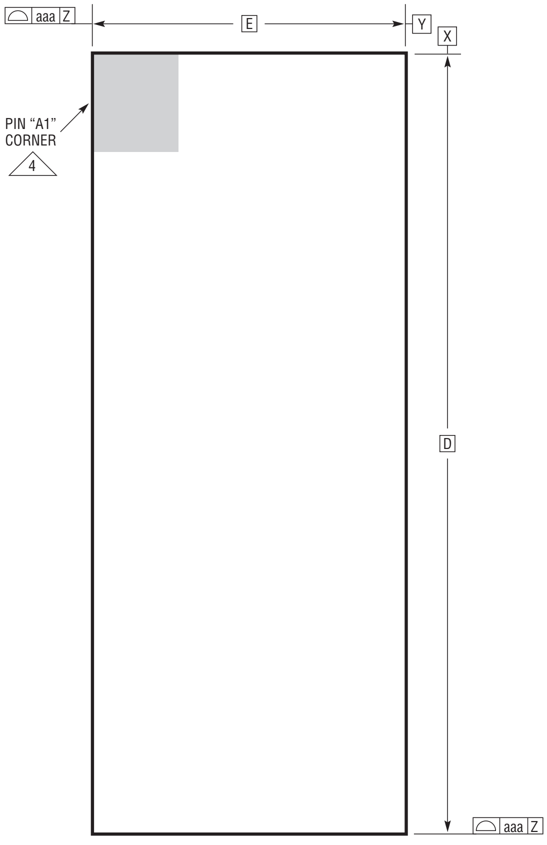
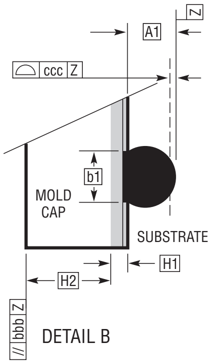
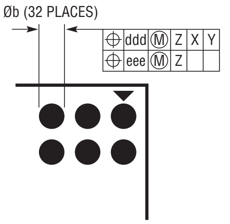
BGA Package
32-Lead (22mm × 9mm × 5.06mm)
(Reference LTC DWG# 05-08-1945 Rev A)



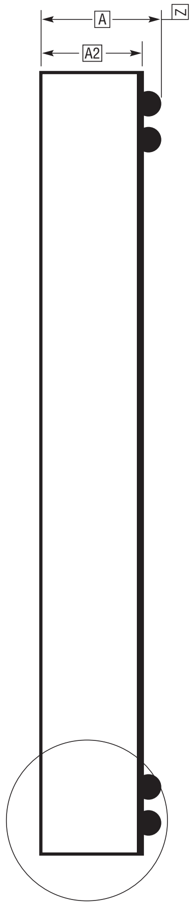
PACKAGE TOP VIEW



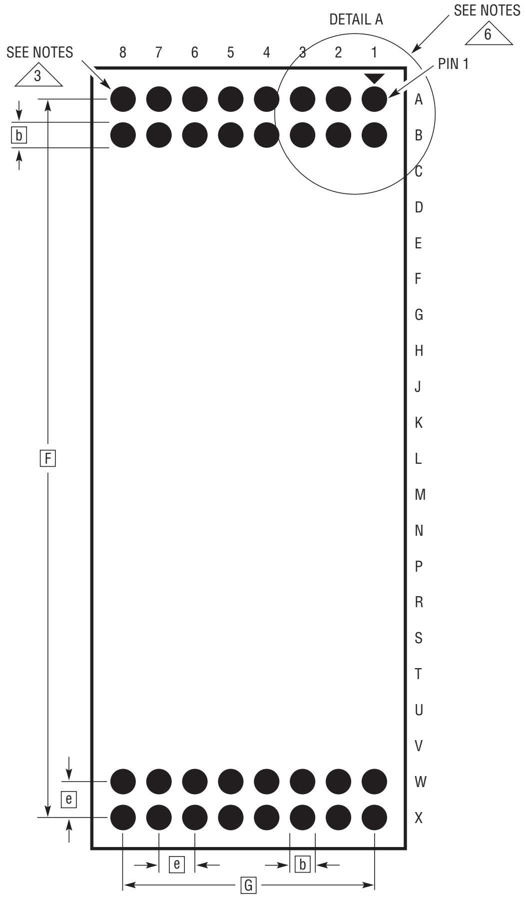
DETAIL B



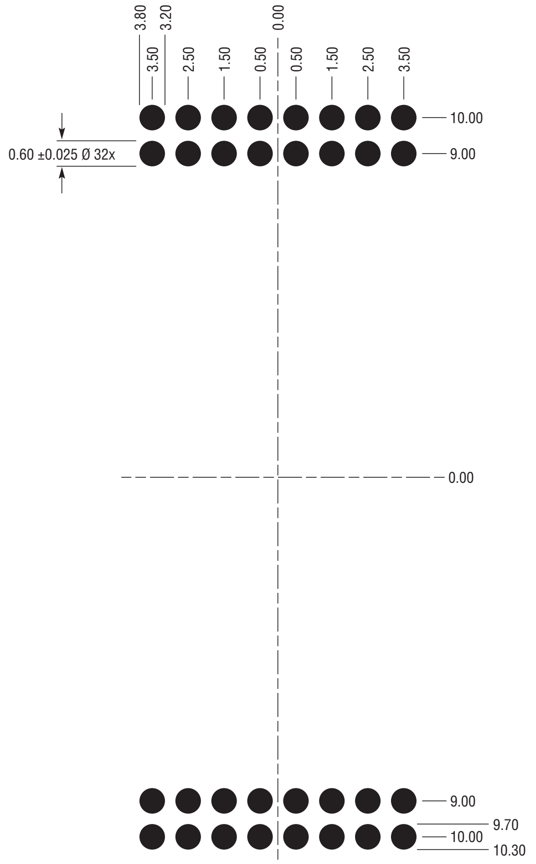
DETAIL A



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	4.76	5.06	5.26	
A1	0.40	0.50	0.60	BALL HT
A2	4.36	4.56	4.66	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		22.0		
E		9.0		
e		1.0		
F		20.0		
G		7.0		
H1	0.46	0.56	0.66	SUBSTRATE THK
H2	3.95	4.00	4.05	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 32				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

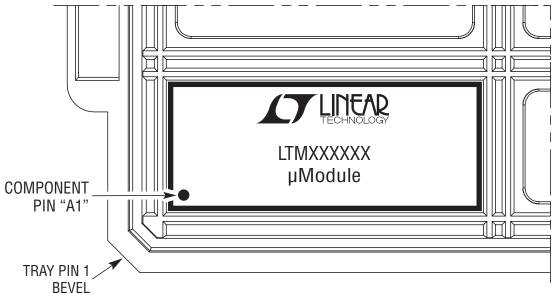
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION